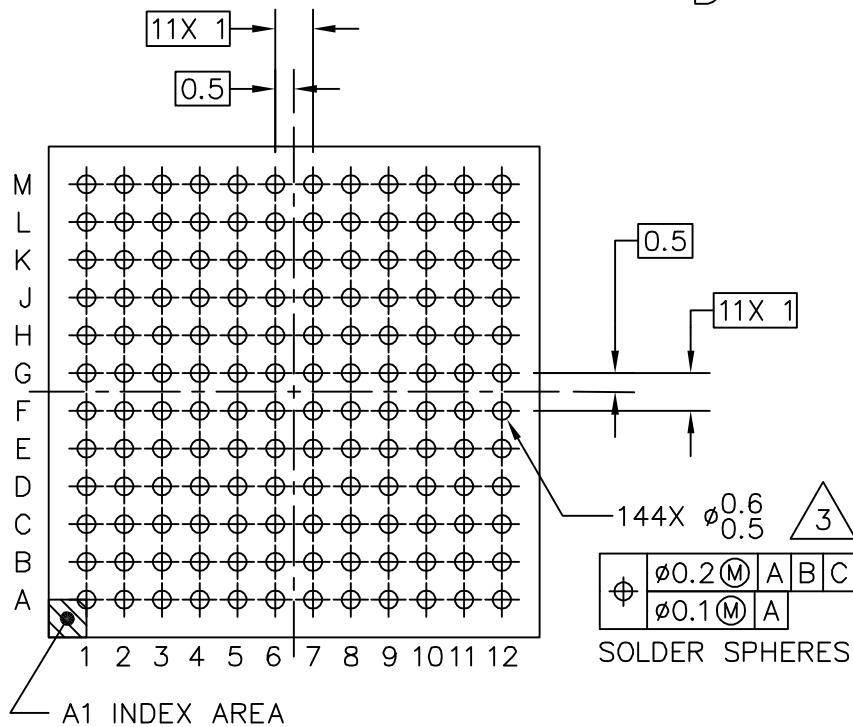
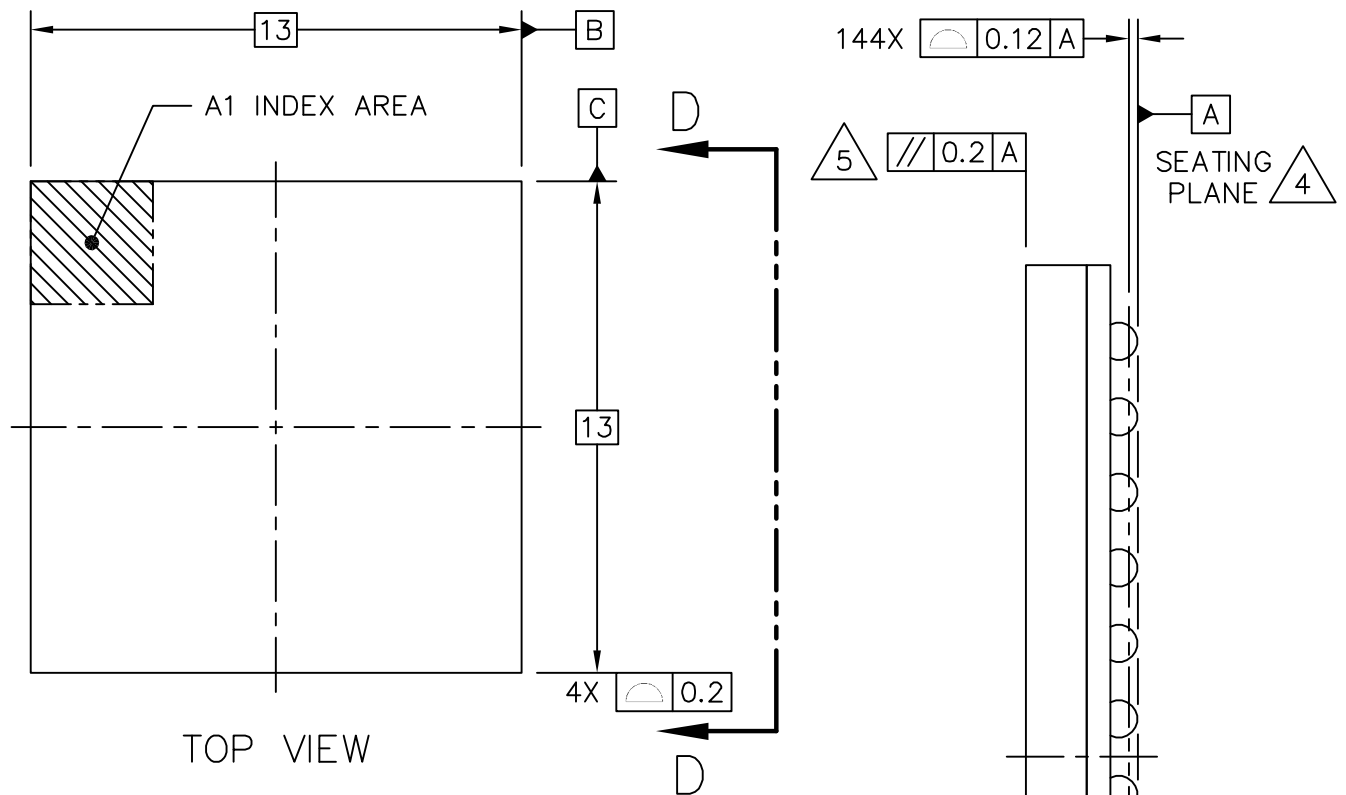
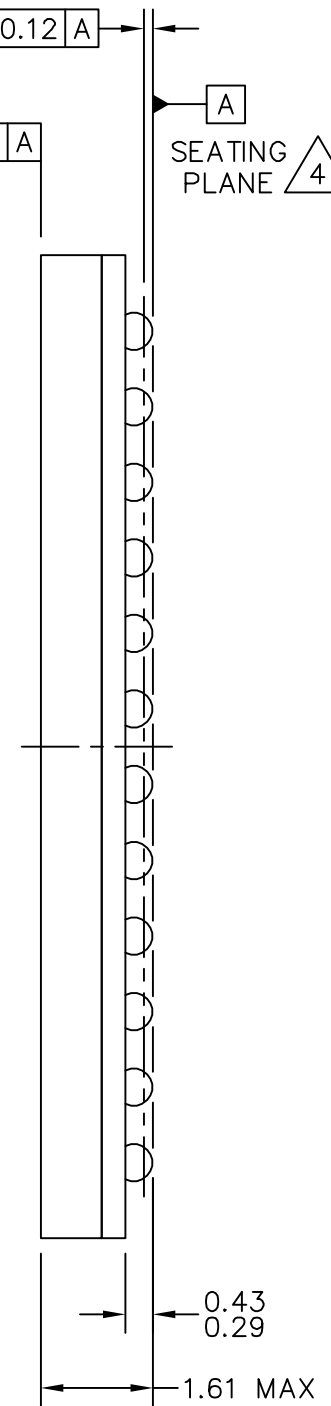




VIEW D-D



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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: MAPBGA,
144 I/O, 13 X 13 X 1.46 PKG,
1 MM PITCH

DOCUMENT NO: 98ASH70694A

REV: F

STANDARD: NON-JEDEC

13 MAY 2013

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: MAPBGA, 144 I/O, 13 X 13 X 1.46 PKG, 1 MM PITCH	DOCUMENT NO: 98ASH70694A REV: F	
	STANDARD: NON–JEDEC	
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